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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, I²C, SCI, SPI
Peripherals	PWM, WDT
Number of I/O	91
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.25V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	112-LQFP
Supplier Device Package	112-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s12dg128mpve

Section 3 System Clock Description

Section 4 Modes of Operation

Section 5 Resets and Interrupts

Section 6 HCS12 Core Block Description

- **Port H**
  In order to avoid floating nodes the ports should be either configured as outputs by setting the data direction register (DDRH at Base+$0262) to $FF, or enabling the pull resistors by writing a $FF to the pull enable register (PERH at Base+$0264).
- **Port J[1:0]**
  Port J pull-up resistors are enabled out of reset on all four pins (7:6 and 1:0). Therefore care must be taken not to disable the pull enables on PJ[1:0] by clearing the bits PERJ1 and PERJ0 at Base+$026C.
- **Port K**
  Port K pull-up resistors are enabled out of reset, i.e. Bit 7 = PUKE = 1 in the register PUCR at Base+$000C. Therefore care must be taken not to clear this bit.
- **Port M[7:6]**
  PM7:6 must be configured as outputs or their pull resistors must be enabled to avoid floating inputs.
- **Port P6**
  PP6 must be configured as output or its pull resistor must be enabled to avoid a floating input.
- **Port S[7:4]**
  PS7:4 must be configured as outputs or their pull resistors must be enabled to avoid floating inputs.
- **PAD[15:8] (ATD1 channels)**
  Out of reset the ATD1 is disabled preventing current flows in the pins. Do not modify the ATD1 registers!

- **Pins not available in 80 pin QFP package for MC9S12DB128, SC515846, and SC102202**
  - **Port H**
    In order to avoid floating nodes the ports should be either configured as outputs by setting the data direction register (DDRH at Base+$0262) to $FF, or enabling the pull resistors by writing a $FF to the pull enable register (PERH at Base+$0264).
  - **Port J[7:6, 1:0]**
    Port J pull-up resistors are enabled out of reset on all four pins (7:6 and 1:0). Therefore care must be taken not to disable the pull enables on PJ[7:6, 1:0] by clearing the bits PERJ7, PERJ6, PERJ1 and PERJ0 at Base+$026C.
  - **Port K**
    Port K pull-up resistors are enabled out of reset, i.e. Bit 7 = PUKE = 1 in the register PUCR at Base+$000C. Therefore care must be taken not to clear this bit.
  - **Port M[1:0]**
    PM1:0 must be configured as outputs or their pull resistors must be enabled to avoid floating inputs.
  - **Port P6**
    PP6 must be configured as output or its pull resistor must be enabled to avoid a floating input.

1.4 Block Diagram

Figure 1-1 shows a block diagram of the MC9S12DT128 device.

$0120 - $013F ATD1 (Analog to Digital Converter 10 Bit 8 Channel)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0130	ATD1DR0H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write:								
$0131	ATD1DR0L	Read:	Bit7	Bit6	0	0	0	0	0	0
		Write:								
$0132	ATD1DR1H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write:								
$0133	ATD1DR1L	Read:	Bit7	Bit6	0	0	0	0	0	0
		Write:								
$0134	ATD1DR2H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write:								
$0135	ATD1DR2L	Read:	Bit7	Bit6	0	0	0	0	0	0
		Write:								
$0136	ATD1DR3H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write:								
$0137	ATD1DR3L	Read:	Bit7	Bit6	0	0	0	0	0	0
		Write:								
$0138	ATD1DR4H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write:								
$0139	ATD1DR4L	Read:	Bit7	Bit6	0	0	0	0	0	0
		Write:								
$013A	ATD1DR5H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write:								
$013B	ATD1DR5L	Read:	Bit7	Bit6	0	0	0	0	0	0
		Write:								
$013C	ATD1DR6H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write:								
$013D	ATD1DR6L	Read:	Bit7	Bit6	0	0	0	0	0	0
		Write:								
$013E	ATD1DR7H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write:								
$013F	ATD1DR7L	Read:	Bit7	Bit6	0	0	0	0	0	0
		Write:								

$0140 - $017F CAN0 (Motorola Scalable CAN - MSCAN)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0140	CAN0CTL0	Read:	RXFRM	RXACT	CSWAI	SYNCH	TIME	WUPE	SLPRQ	INITRQ
		Write:								
$0141	CAN0CTL1	Read:	CANE	CLKSRC	LOOPB	LISTEN	0	WUPM	SLPAK	INITAK
		Write:								
$0142	CAN0BTR0	Read:	SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0
		Write:								
$0143	CAN0BTR1	Read:	SAMP	TSEG22	TSEG21	TSEG20	TSEG13	TSEG12	TSEG11	TSEG10
		Write:								
$0144	CAN0RFLG	Read:	WUPIF	CSCIF	RSTAT1	RSTAT0	TSTAT1	TSTAT0	OVRIF	RXF
		Write:								
$0145	CAN0RIER	Read:	WUPIE	CSCIE	RSTATE1	RSTATE0	TSTATE1	TSTATE0	OVRIE	RXFIE
		Write:								

$0240 - $027F PIM (Port Integration Module)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0259	PTIP	Read:	PTIP7	PTIP6	PTIP5	PTIP4	PTIP3	PTIP2	PTIP1	PTIP0
		Write:								
$025A	DDRP	Read:	DDRP7	DDRP7	DDRP5	DDRP4	DDRP3	DDRP2	DDRP1	DDRP0
		Write:								
$025B	RDRP	Read:	RDRP7	RDRP6	RDRP5	RDRP4	RDRP3	RDRP2	RDRP1	RDRP0
		Write:								
$025C	PERP	Read:	PERP7	PERP6	PERP5	PERP4	PERP3	PERP2	PERP1	PERP0
		Write:								
$025D	PPSP	Read:	PPSP7	PPSP6	PPSP5	PPSP4	PPSP3	PPSP2	PPSP1	PPSS0
		Write:								
$025E	PIEP	Read:	PIEP7	PIEP6	PIEP5	PIEP4	PIEP3	PIEP2	PIEP1	PIEP0
		Write:								
$025F	PIFP	Read:	PIFP7	PIFP6	PIFP5	PIFP4	PIFP3	PIFP2	PIFP1	PIFP0
		Write:								
$0260	PTH	Read:	PTH7	PTH6	PTH5	PTH4	PTH3	PTH2	PTH1	PTH0
		Write:								
$0261	PTIH	Read:	PTIH7	PTIH6	PTIH5	PTIH4	PTIH3	PTIH2	PTIH1	PTIH0
		Write:								
$0262	DDRH	Read:	DDRH7	DDRH7	DDRH5	DDRH4	DDRH3	DDRH2	DDRH1	DDRH0
		Write:								
$0263	RDRH	Read:	RDRH7	RDRH6	RDRH5	RDRH4	RDRH3	RDRH2	RDRH1	RDRH0
		Write:								
$0264	PERH	Read:	PERH7	PERH6	PERH5	PERH4	PERH3	PERH2	PERH1	PERH0
		Write:								
$0265	PPSH	Read:	PPSH7	PPSH6	PPSH5	PPSH4	PPSH3	PPSH2	PPSH1	PPSH0
		Write:								
$0266	PIEH	Read:	PIEH7	PIEH6	PIEH5	PIEH4	PIEH3	PIEH2	PIEH1	PIEH0
		Write:								
$0267	PIFH	Read:	PIFH7	PIFH6	PIFH5	PIFH4	PIFH3	PIFH2	PIFH1	PIFH0
		Write:								
$0268	PTJ	Read:	PTJ7	PTJ6	0	0	0	0	PTJ1	PTJ0
		Write:								
$0269	PTIJ	Read:	PTIJ7	PTIJ6	0	0	0	0	PTIJ1	PTIJ0
		Write:								
$026A	DDRJ	Read:	DDRJ7	DDRJ7	0	0	0	0	DDRJ1	DDRJ0
		Write:								
$026B	RDRJ	Read:	RDRJ7	RDRJ6	0	0	0	0	RDRJ1	RDRJ0
		Write:								
$026C	PERJ	Read:	PERJ7	PERJ6	0	0	0	0	PERJ1	PERJ0
		Write:								
$026D	PPSJ	Read:	PPSJ7	PPSJ6	0	0	0	0	PPSJ1	PPSJ0
		Write:								
$026E	PIEJ	Read:	PIEJ7	PIEJ6	0	0	0	0	PIEJ1	PIEJ0
		Write:								
$026F	PIFJ	Read:	PIFJ7	PIFJ6	0	0	0	0	PIFJ1	PIFJ0
		Write:								
$0270 - $027F	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$02C0 - $02FF Reserved

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$02C0 - $02FF	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$0300 - $035F Byteflight

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0300	BFMCR	Read:	INITRQ	MASTER	ALARM	SLPAK	SLPRQ	WPULSE	SSWAI	INITAK
		Write:								
$0301	BFFSIZR	Read:	0	0	0	FSIZ4	FSIZ3	FSIZ2	FSIZ1	FSIZ0
		Write:								
$0302	BFTCR1	Read:	TWX0T7	TWX0T6	TWX0T5	TWX0T4	TWX0T3	TWX0T2	TWX0T1	TWX0T0
		Write:								
$0303	BFTCR2	Read:	TWX0R7	TWX0R6	TWX0R5	TWX0R4	TWX0R3	TWX0R2	TWX0R1	TWX0R0
		Write:								
$0304	BFTCR3	Read:	TWX0D7	TWX0D6	TWX0D5	TWX0D4	TWX0D3	TWX0D2	TWX0D1	TWX0D0
		Write:								
$0305	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$0306	BFRISR	Read:	RCVFIF	RXIF	SYNAIF	SYNNIF	SLMMIF	0	XSYNIF	OPTDF
		Write:								
$0307	BFGISR	Read:	TXIF	OVRNIF	ERRIF	SYNEIF	SYNLIF	ILLPIF	LOCKIF	WAKEIF
		Write:								
$0308	BFRIER	Read:	RCVFIE	RXIE	SYNAIE	SYNNIE	SLMMIE	0	XSYNIE	0
		Write:								
$0309	BFGIER	Read:	TXIE	OVRNIE	ERRIE	SYNEIE	SYNLIE	ILLPIE	LOCKIE	WAKEIE
		Write:								
$030A	BFRIVEC	Read:	0	0	0	0	RIVEC3	RIVEC2	RIVEC1	RIVEC0
		Write:								
$030B	BFTIVEC	Read:	0	0	0	0	TIVEC3	TIVEC2	TIVEC1	TIVEC0
		Write:								
$030C	BFFIDAC	Read:	FIDAC7	FIDAC6	FIDAC5	FIDAC4	FIDAC3	FIDAC2	FIDAC1	FIDAC0
		Write:								
$030D	BFFIDMR	Read:	FIDMR7	FIDMR6	FIDMR5	FIDMR4	FIDMR3	FIDMR2	FIDMR1	FIDMR0
		Write:								
$030E	BFMVR	Read:	MVR7	MVR6	MVR5	MVR4	MVR3	MVR2	MVR1	MVR0
		Write:								
$030F	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$0310	BFPCTLBF	Read:	PMEREN	0	PSLMEN	PERREN	PROKEN	PSYNEN	0	BFEN
		Write:								
$0311	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$0312	BFBUFLOCK	Read:	0	0	0	0	0	0	TXBUFLOCK	RXBUFLOCK
		Write:								
$0313	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$0314	BFFIDRJ	Read:	FIDRJ7	FIDRJ6	FIDRJ5	FIDRJ4	FIDRJ3	FIDRJ2	FIDRJ1	FIDRJ0
		Write:								

2.3.6 PAD[15] / AN1[7] / ETRIG1 — Port AD Input Pin [15]

PAD15 is a general purpose input pin and analog input of the analog to digital converter ATD1. It can act as an external trigger input for the ATD1.

2.3.7 PAD[14:8] / AN1[6:0] — Port AD Input Pins [14:8]

PAD14 - PAD8 are general purpose input pins and analog inputs of the analog to digital converter ATD1.

2.3.8 PAD[7] / AN0[7] / ETRIG0 — Port AD Input Pin [7]

PAD7 is a general purpose input pin and analog input of the analog to digital converter ATD0. It can act as an external trigger input for the ATD0.

2.3.9 PAD[6:0] / AN0[6:0] — Port AD Input Pins [6:0]

PAD6 - PAD8 are general purpose input pins and analog inputs of the analog to digital converter ATD0.

2.3.10 PA[7:0] / ADDR[15:8] / DATA[15:8] — Port A I/O Pins

PA7-PA0 are general purpose input or output pins. In MCU expanded modes of operation, these pins are used for the multiplexed external address and data bus.

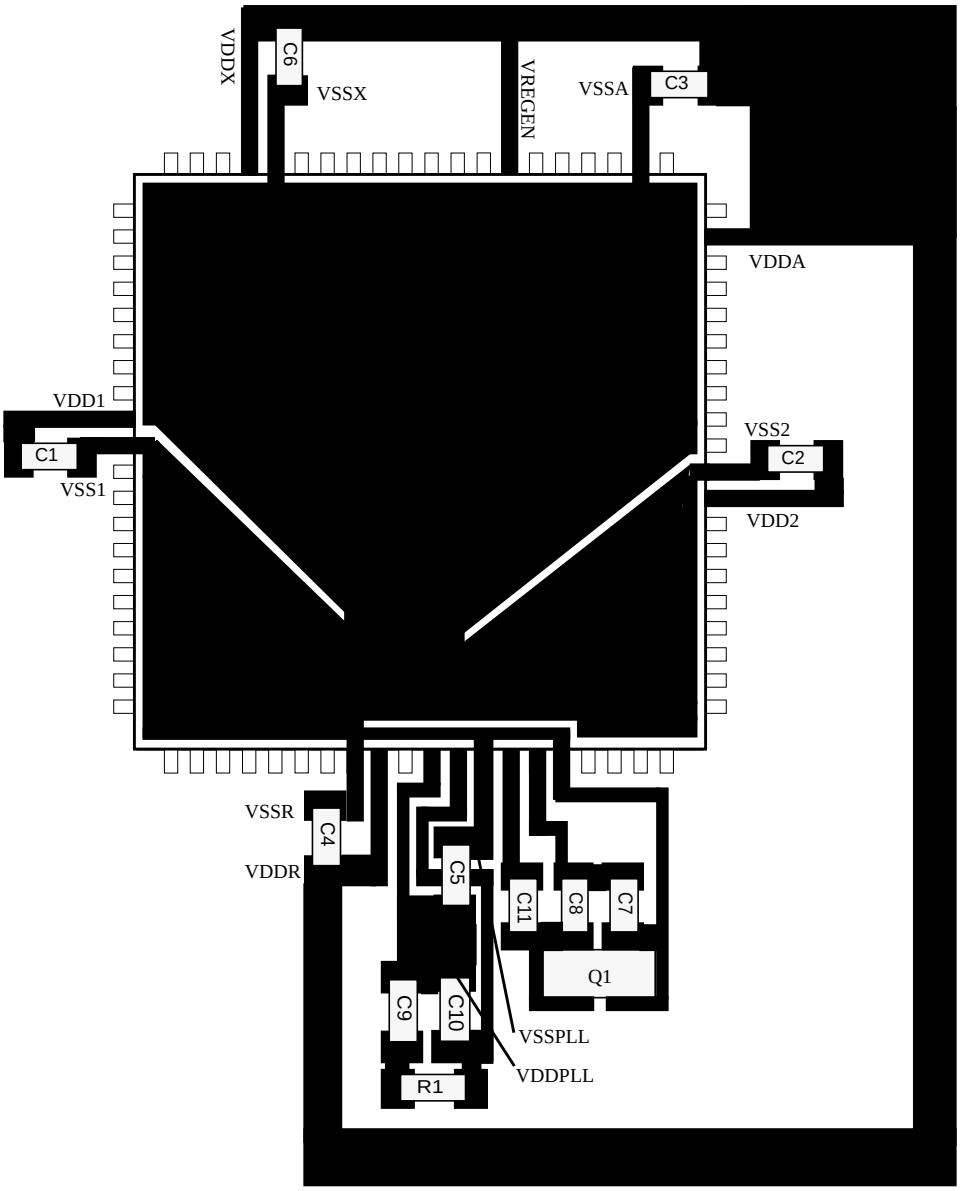
2.3.11 PB[7:0] / ADDR[7:0] / DATA[7:0] — Port B I/O Pins

PB7-PB0 are general purpose input or output pins. In MCU expanded modes of operation, these pins are used for the multiplexed external address and data bus.

2.3.12 PE7 / NOACC / $\overline{\text{XCLKS}}$ — Port E I/O Pin 7

PE7 is a general purpose input or output pin. During MCU expanded modes of operation, the NOACC signal, when enabled, is used to indicate that the current bus cycle is an unused or “free” cycle. This signal will assert when the CPU is not using the bus.
The $\overline{\text{XCLKS}}$ is an input signal which controls whether a crystal in combination with the internal Colpitts (low power) oscillator is used or whether Pierce oscillator/external clock circuitry is used. The state of this pin is latched at the rising edge of $\overline{\text{RESET}}$. If the input is a logic low the EXTAL pin is configured for an external clock drive. If input is a logic high an oscillator circuit is configured on EXTAL and XTAL. Since this pin is an input with a pull-up device during reset, if the pin is left floating, the default configuration is an oscillator circuit on EXTAL and XTAL.

Figure 23-2 Recommended PCB Layout for 80QFP (MC9S12DG128E, MC9S12DG128, MC9S12DJ128E, MC9S12DJ128, MC9S12A128, SC515847, SC515848, SC101161DG, SC101161DJ, SC102203, and SC102204) Colpitts Oscillator



NOTE: *In the following context VDD5 is used for either VDDA, VDDR and VDDX; VSS5 is used for either VSSA, VSSR and VSSX unless otherwise noted.*
IDD5 denotes the sum of the currents flowing into the VDDA, VDDX and VDDR pins.
VDD is used for VDD1, VDD2 and VDDPLL, VSS is used for VSS1, VSS2 and VSSPLL.
IDD is used for the sum of the currents flowing into VDD1 and VDD2.

A.1.3 Pins

There are four groups of functional pins.

A.1.3.1 5V I/O pins

Those I/O pins have a nominal level of 5V. This class of pins is comprised of all port I/O pins, the analog inputs, BKGD pin and the RESET inputs.The internal structure of all those pins is identical, however some of the functionality may be disabled. E.g. for the analog inputs the output drivers, pull-up and pull-down resistors are disabled permanently.

A.1.3.2 Analog Reference

This class is made up by the two VRH and VRL pins.

A.1.3.3 Oscillator

The pins XFC, EXTAL, XTAL dedicated to the oscillator have a nominal 2.5V level. They are supplied by VDDPLL.

A.1.3.4 TEST

This pin is used for production testing only.

A.1.3.5 VREGEN

This pin is used to enable the on chip voltage regulator.

A.1.4 Current Injection

Power supply must maintain regulation within operating V_{DD5} or V_{DD} range during instantaneous and operating maximum current conditions. If positive injection current ($V_{in} > V_{DD5}$) is greater than I_{DD5}, the injection current may flow out of VDD5 and could result in external power supply going out of regulation. Insure external VDD5 load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power; e.g. if no system clock is present, or if clock rate is very low which would reduce overall power consumption.

A.1.5 Absolute Maximum Ratings

Absolute maximum ratings are stress ratings only. A functional operation under or outside those maxima is not guaranteed. Stress beyond those limits may affect the reliability or cause permanent damage of the device.

This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., either V_{SS5} or V_{DD5}).

Table A-1 Absolute Maximum Ratings[1]

Num	Rating	Symbol	Min	Max	Unit
1	I/O, Regulator and Analog Supply Voltage	V_{DD5}	-0.3	6.0	V
2	Digital Logic Supply Voltage [2]	V_{DD}	-0.3	3.0	V
3	PLL Supply Voltage [(2)]	V_{DDPLL}	-0.3	3.0	V
4	Voltage difference VDDX to VDDR and VDDA	Δ_{VDDX}	-0.3	0.3	V
5	Voltage difference VSSX to VSSR and VSSA	Δ_{VSSX}	-0.3	0.3	V
6	Digital I/O Input Voltage	V_{IN}	-0.3	6.0	V
7	Analog Reference	$V_{RH,}$ V_{RL}	-0.3	6.0	V
8	XFC, EXTAL, XTAL inputs	V_{ILV}	-0.3	3.0	V
9	TEST input	V_{TEST}	-0.3	10.0	V
10	Instantaneous Maximum Current Single pin limit for all digital I/O pins [3]	I_D	-25	+25	mA
11	Instantaneous Maximum Current Single pin limit for XFC, EXTAL, XTAL[4]	I_{DL}	-25	+25	mA
12	Instantaneous Maximum Current Single pin limit for TEST [5]	I_{DT}	-0.25	0	mA
13	Storage Temperature Range	T_{stg}	– 65	155	°C

NOTES:
1. Beyond absolute maximum ratings device might be damaged.
2. The device contains an internal voltage regulator to generate the logic and PLL supply out of the I/O supply. The absolute maximum ratings apply when the device is powered from an external source.
3. All digital I/O pins are internally clamped to V_{SSX} and V_{DDX}, V_{SSR} and V_{DDR} or V_{SSA} and V_{DDA}.
4. Those pins are internally clamped to V_{SSPLL} and V_{DDPLL}.
5. This pin is clamped low to V_{SSX}, but not clamped high. This pin must be tied low in applications.

A.1.6 ESD Protection and Latch-up Immunity

All ESD testing is in conformity with CDF-AEC-Q100 Stress test qualification for Automotive Grade Integrated Circuits. During the device qualification ESD stresses were performed for the Human Body Model (HBM), the Machine Model (MM) and the Charge Device Model.

A.1.10.1 Measurement Conditions

All measurements are without output loads. Unless otherwise noted the currents are measured in single chip mode, internal voltage regulator enabled and at 25MHz bus frequency using a 4MHz oscillator in Colpitts mode. Production testing is performed using a square wave signal at the EXTAL input.

A.1.10.2 Additional Remarks

In expanded modes the currents flowing in the system are highly dependent on the load at the address, data and control signals as well as on the duty cycle of those signals. No generally applicable numbers can be given. A very good estimate is to take the single chip currents and add the currents due to the external loads.

Table A-7 Supply Current Characteristics

Conditions are shown in **(Table A-4)** unless otherwise noted							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	Run supply currents Single Chip, Internal regulator enabled	I_{DD5}			55	mA
2	P P	Wait Supply current All modules enabled, PLL on only RTI enabled (1)	I_{DDW}			30 5	mA
3	 C P C C P C P C P	Pseudo Stop Current (RTI and COP disabled) 1, 2 -40°C 27°C 70°C 85°C “C” Temp Option 100°C 105°C “V” Temp Option 120°C 125°C “M” Temp Option 140°C	I_{DDPS}		 370 400 450 550 600 650 800 850 1200	 500 1600 2100 5000	µA
4	 C C C C C C C	Pseudo Stop Current (RTI and COP enabled) (1), (2) -40°C 27°C 70°C 85°C 105°C 125°C 140°C	I_{DDPS}		 570 600 650 750 850 1200 1500		µA
5	 C P C C P C P C P	Stop Current (2) -40°C 27°C 70°C 85°C “C” Temp Option 100°C 105°C “V” Temp Option 120°C 125°C “M” Temp Option 140°C	I_{DDS}		 12 25 100 130 160 200 350 400 600	 100 1200 1700 5000	µA

A.3 NVM, Flash and EEPROM

NOTE: *Unless otherwise noted the abbreviation NVM (Non Volatile Memory) is used for both Flash and EEPROM.*

A.3.1 NVM timing

The time base for all NVM program or erase operations is derived from the oscillator. A minimum oscillator frequency f_{NVMOSC} is required for performing program or erase operations. The NVM modules do not have any means to monitor the frequency and will not prevent program or erase operation at frequencies above or below the specified minimum. Attempting to program or erase the NVM modules at a lower frequency a full program or erase transition is not assured.

The Flash and EEPROM program and erase operations are timed using a clock derived from the oscillator using the FCLKDIV and ECLKDIV registers respectively. The frequency of this clock must be set within the limits specified as f_{NVMOP}.

The minimum program and erase times shown in **(Table A-11)** are calculated for maximum f_{NVMOP} and maximum f_{bus}. The maximum times are calculated for minimum f_{NVMOP} and a f_{bus} of 2MHz.

A.3.1.1 Single Word Programming

The programming time for single word programming is dependant on the bus frequency as a well as on the frequency f_{NVMOP} and can be calculated according to the following formula.

$$t_{swpgm} = 9 \cdot \frac{1}{f_{NVMOP}} + 25 \cdot \frac{1}{f_{bus}}$$

A.3.1.2 Row Programming

This applies only to the Flash where up to 32 words in a row can be programmed consecutively by keeping the command pipeline filled. The time to program a consecutive word can be calculated as:

$$t_{bwpgm} = 4 \cdot \frac{1}{f_{NVMOP}} + 9 \cdot \frac{1}{f_{bus}}$$

The time to program a whole row is:

$$t_{brpgm} = t_{swpgm} + 31 \cdot t_{bwpgm}$$

Row programming is more than 2 times faster than single word programming.

A.3.1.3 Sector Erase

Erasing a 512 byte Flash sector or a 4 byte EEPROM sector takes:

A.6 MSCAN

Table A-17 MSCAN Wake-up Pulse Characteristics

Conditions are shown in **(Table A-4)** unless otherwise noted							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	MSCAN Wake-up dominant pulse filtered	t_{WUP}			2	µs
2	P	MSCAN Wake-up dominant pulse pass	t_{WUP}	5			µs

A.7.2 Slave Mode

Figure A-8 and **Figure A-9** illustrate the slave mode timing. Timing values are shown in **(Table A-19)**.

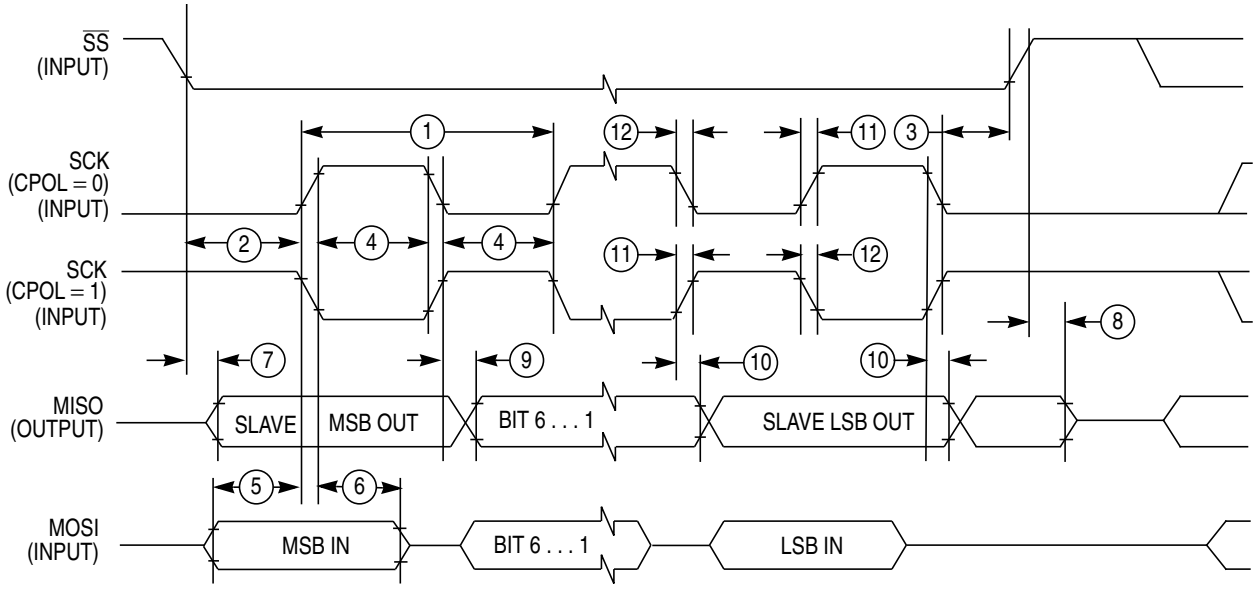


Figure A-8 SPI Slave Timing (CPHA = 0)

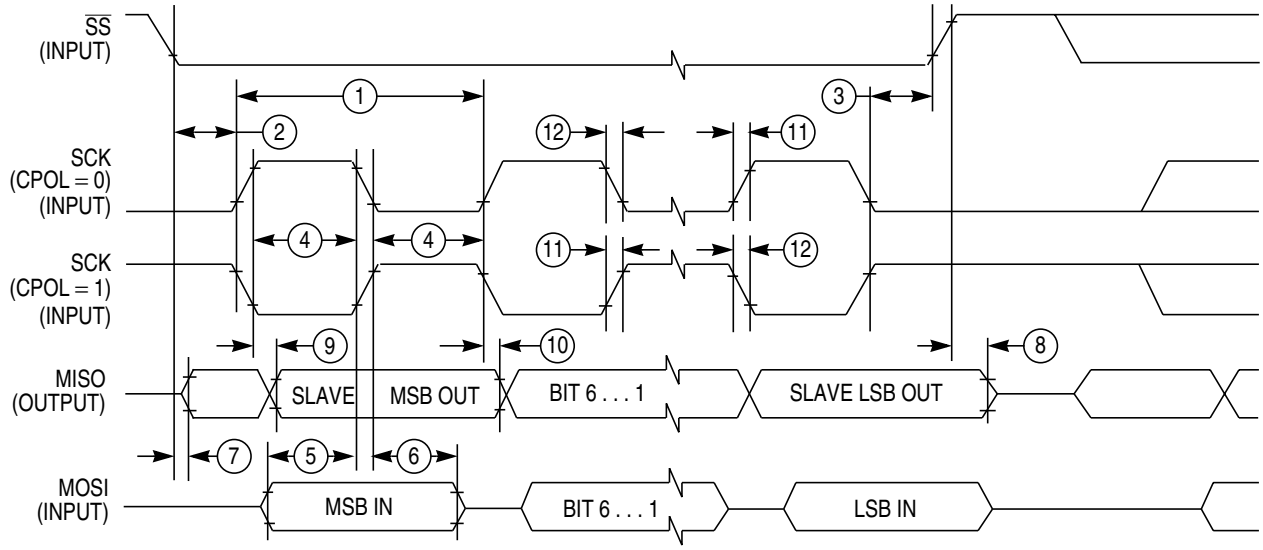


Figure A-9 SPI Slave Timing (CPHA =1)

Table A-19 SPI Slave Mode Timing Characteristics

Conditions are shown in **(Table A-4)** unless otherwise noted, CLOAD = 200pF on all outputs							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	Operating Frequency	f_{op}	DC		1/4	f_{bus}
1	P	SCK Period $t_{sck} = 1./f_{op}$	t_{sck}	4		2048	t_{bus}
2	D	Enable Lead Time	t_{lead}	1			t_{cyc}
3	D	Enable Lag Time	t_{lag}	1			t_{cyc}
4	D	Clock (SCK) High or Low Time	t_{wsck}	$t_{cyc} – 30$			ns
5	D	Data Setup Time (Inputs)	t_{su}	25			ns
6	D	Data Hold Time (Inputs)	t_{hi}	25			ns
7	D	Slave Access Time	t_a			1	t_{cyc}
8	D	Slave MISO Disable Time	t_{dis}			1	t_{cyc}
9	D	Data Valid (after SCK Edge)	t_v			25	ns
10	D	Data Hold Time (Outputs)	t_{ho}	0			ns
11	D	Rise Time Inputs and Outputs	t_r			25	ns
12	D	Fall Time Inputs and Outputs	t_f			25	ns

A.8 External Bus Timing

A timing diagram of the external multiplexed-bus is illustrated in **Figure A-10** with the actual timing values shown on table **(Table A-20)**. All major bus signals are included in the diagram. While both a data write and data read cycle are shown, only one or the other would occur on a particular bus cycle.

A.8.1 General Multiplexed Bus Timing

The expanded bus timings are highly dependent on the load conditions. The timing parameters shown assume a balanced load across all outputs.

Table A-20 Expanded Bus Timing Characteristics

Conditions are shown in **(Table A-4)** unless otherwise noted, C_{LOAD} = 50pF							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	Frequency of operation (E-clock)	f_o	0		25.0	MHz
2	P	Cycle time	t_{cyc}	40			ns
3	D	Pulse width, E low	PW_{EL}	19			ns
4	D	Pulse width, E high[1]	PW_{EH}	19			ns
5	D	Address delay time	t_{AD}			8	ns
6	D	Address valid time to E rise (PW_{EL}–t_{AD})	t_{AV}	11			ns
7	D	Muxed address hold time	t_{MAH}	2			ns
8	D	Address hold to data valid	t_{AHDS}	7			ns
9	D	Data hold to address	t_{DHA}	2			ns
10	D	Read data setup time	t_{DSR}	13			ns
11	D	Read data hold time	t_{DHR}	0			ns
12	D	Write data delay time	t_{DDW}			7	ns
13	D	Write data hold time	t_{DHW}	2			ns
14	D	Write data setup time(1) (PW_{EH}–t_{DDW})	t_{DSW}	12			ns
15	D	Address access time(1) (t_{cyc}–t_{AD}–t_{DSR})	t_{ACCA}	19			ns
16	D	E high access time(1) (PW_{EH}–t_{DSR})	t_{ACCE}	6			ns
17	D	Non-multiplexed address delay time	t_{NAD}			6	ns
18	D	Non-muxed address valid to E rise (PW_{EL}–t_{NAD})	t_{NAV}	15			ns
19	D	Non-multiplexed address hold time	t_{NAH}	2			ns
20	D	Chip select delay time	t_{CSD}			16	ns
21	D	Chip select access time(1) (t_{cyc}–t_{CSD}–t_{DSR})	t_{ACCS}	11			ns
22	D	Chip select hold time	t_{CSH}	2			ns
23	D	Chip select negated time	t_{CSN}	8			ns
24	D	Read/write delay time	t_{RWD}			7	ns
25	D	Read/write valid time to E rise (PW_{EL}–t_{RWD})	t_{RWV}	14			ns
26	D	Read/write hold time	t_{RWH}	2			ns
27	D	Low strobe delay time	t_{LSD}			7	ns
28	D	Low strobe valid time to E rise (PW_{EL}–t_{LSD})	t_{LSV}	14			ns
29	D	Low strobe hold time	t_{LSH}	2			ns
30	D	NOACC strobe delay time	t_{NOD}			7	ns
31	D	NOACC valid time to E rise (PW_{EL}–t_{NOD})	t_{NOV}	14			ns

Appendix B Package Information

B.1 General

This section provides the physical dimensions of the MC9S12DT128 packages.